

# FMP05N60E

**FUJI POWER MOSFET** 

## Super FAP-E<sup>3</sup> series

## **N-CHANNEL SILICON POWER MOSFET**

#### ■ Features

Maintains both low power loss and low noise Lower R<sub>DS</sub>(on) characteristic More controllable switching dv/dt by gate resistance Smaller V<sub>GS</sub> ringing waveform during switching Narrow band of the gate threshold voltage (3.0±0.5V) High avalanche durability

### Applications

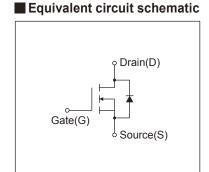
Switching regulators UPS (Uninterruptible Power Supply) DC-DC converters

## Maximum Ratings and Characteristics

## ● Absolute Maximum Ratings at Tc=25°C (unless otherwise specified)

## TO-220AB 83.610 åee Note:1. 0.4 8-2 2.7 10.2 123

■ Outline Drawings [mm]



Description	Symbol	Characteristics	Unit	Remarks
Proin Source Voltage	V <sub>DS</sub>	600	V	
Drain-Source Voltage	V <sub>DSX</sub>	600	V	V <sub>GS</sub> = -30V
Continuous Drain Current	ID	±5.5	А	
Pulsed Drain Current	IDP	±22	Α	
Gate-Source Voltage	V <sub>GS</sub>	±30	V	
Repetitive and Non-Repetitive Maximum AvalancheCurrent	IAR	5.5	Α	Note*1
Non-Repetitive Maximum Avalanche Energy	Eas	262	mJ	Note*2
Repetitive Maximum Avalanche Energy	Ear	9.0	mJ	Note*3
Peak Diode Recovery dV/dt	dV/dt	4.2	kV/μs	Note*4
Peak Diode Recovery -di/dt	-di/dt	100	A/µs	Note*5
Maximum Power Dissipation	PD	2.02	10/	Ta=25°C
		90	W	Tc=25°C
O	Tch	150	°C	
Operating and Storage Temperature range	Tstg	-55 to + 150	°C	

#### ● Electrical Characteristics at Tc=25°C (unless otherwise specified)

Description	Symbol	Conditions		min.	typ.	max.	Unit	
Drain-Source Breakdown Voltage	BVoss	I <sub>D</sub> =250μA, V <sub>GS</sub> =0V		600	-	-	V	
Gate Threshold Voltage	V <sub>GS</sub> (th)	In=250µA, Vns=Vgs	I <sub>D</sub> =250µA, V <sub>DS</sub> =V <sub>GS</sub>		3.0	3.5	V	
Zana Cata Valtana Busin Comment		V <sub>DS</sub> =600V, V <sub>GS</sub> =0V	T <sub>ch</sub> =25°C	-	-	25		
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> =480V, V <sub>GS</sub> =0V	T <sub>ch</sub> =125°C	-	-	250	μA	
Gate-Source Leakage Current	Igss	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V		10	100	nA	
Drain-Source On-State Resistance	R <sub>DS</sub> (on)	I <sub>D</sub> =2.8A, V <sub>GS</sub> =10V	I <sub>D</sub> =2.8A, V <sub>GS</sub> =10V		1.11	1.30	Ω	
Forward Transconductance	<b>g</b> fs	I <sub>D</sub> =2.8A, V <sub>DS</sub> =25V		3	6	-	S	
Input Capacitance	Ciss	V <sub>DS</sub> =25V		-	1020	1530	pF	
Output Capacitance	Coss	V <sub>GS</sub> =0V	V <sub>GS</sub> =0V		95	143		
Reverse Transfer Capacitance	Crss	f=1MHz		-	7	10.5	7	
Turn-On Time	td(on)	$V_{cs}$ =300V $V_{ds}$ =10V $I_{D}$ =2.8A $R_{cs}$ =24 $\Omega$		-	11	16.5	ns	
	tr			-	8.5	13		
Turn-Off Time	td(off)			-	80	120		
	tf			-	17	25.5		
Total Gate Charge	QG	V <sub>cc</sub> =300V		-	33	50	nC	
Gate-Source Charge	Qss	ID=5.5A	I <sub>D</sub> =5.5A		8.5	13		
Gate-Drain Charge	Q <sub>GD</sub>	V <sub>GS</sub> =10V		-	9.5	14.5		
Avalanche Capability	lav	L=6.35mH, Tch=25°C	L=6.35mH, Tch=25°C		-	-	А	
Diode Forward On-Voltage	V <sub>SD</sub>	I <sub>F</sub> =5.5A, V <sub>GS</sub> =0V, T <sub>ch</sub> =25	I <sub>F</sub> =5.5A, V <sub>GS</sub> =0V, T <sub>ch</sub> =25°C		0.86	1.30	V	
Reverse Recovery Time	trr	I <sub>F</sub> =5.5A, V <sub>GS</sub> =0V	I <sub>F</sub> =5.5A, V <sub>GS</sub> =0V		0.4	-	μS	
Reverse Recovery Charge	Qrr	-di/dt=100A/µs, Tch=25°C		-	3.0	-	μC	

#### Thermal Characteristics

The man end determined								
Description	Symbol Test Condit		min.	typ.	max.	Unit		
Thermal resistance	Rth (ch-c)	Channel to Case			1.390	°C/W		
Thermal resistance	Rth (ch-a)	Channel to Ambient			62.0	°C/W		

Note \*1 : Tch≤150°C

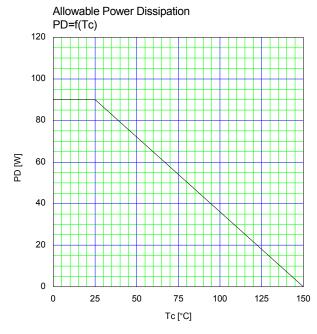
Note \*2 : Stating Tch=25°C, Ias=2.2A, L=99.2mH, Vcc=60V, R<sub>S</sub>=50Ω
Eas limited by maximum channel temperature and avalanche current.
See to 'Avalanche Energy' graph.

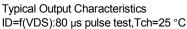
Note \*3 : Repetitive rating : Pulse width limited by maximum channel temperature.

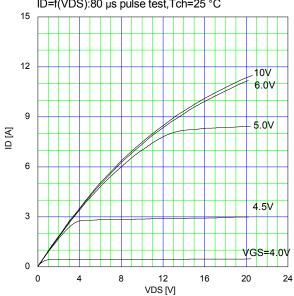
See to the 'Transient Themal impeadance' graph.

Note \*4 : I₅≤-I₀, -di/dt=100A/μ₅, Vcc≤BVbss, Tch≤150°C.

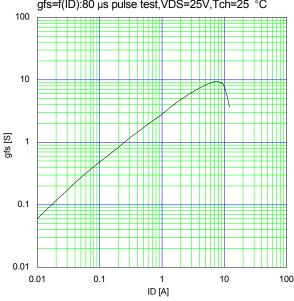
Note \*5 :I₅≤-I₀, dv/dt=4.2kV/μ₅, Vcc≤BVbss, Tch≤150°C.

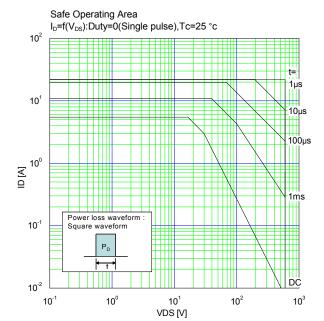




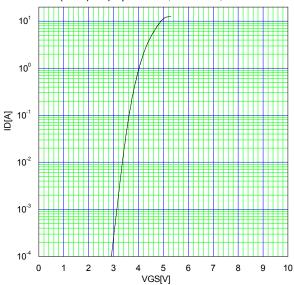


Typical Transconductance gfs=f(ID):80 µs pulse test,VDS=25V,Tch=25 °C

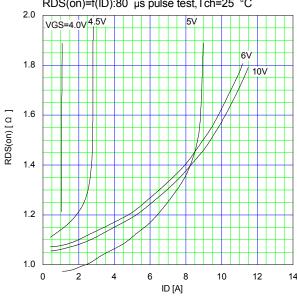




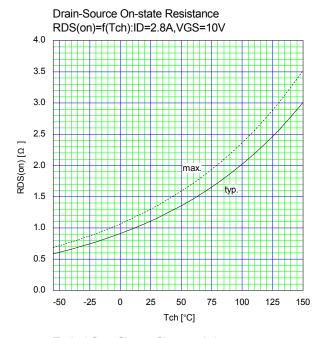
Typical Transfer Characteristic ID=f(VGS):80 µs pulse test,VDS=25V,Tch=25 °C

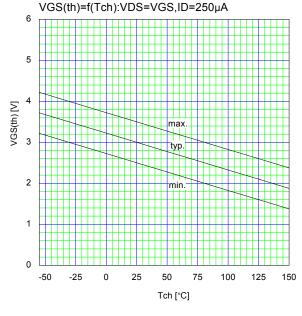


Typical Drain-Source on-state Resistance RDS(on)=f(ID):80 µs pulse test,Tch=25 °C

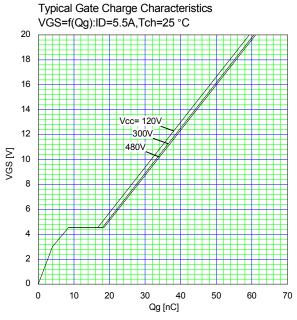


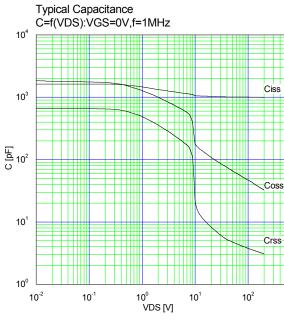
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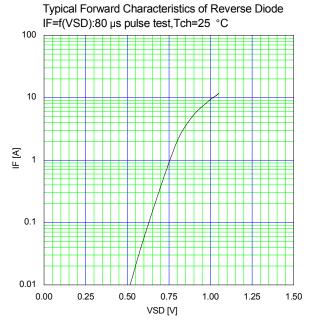


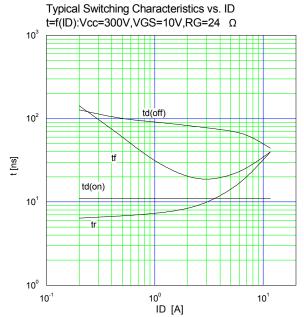


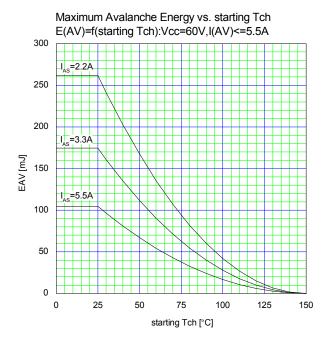
Gate Threshold Voltage vs. Tch

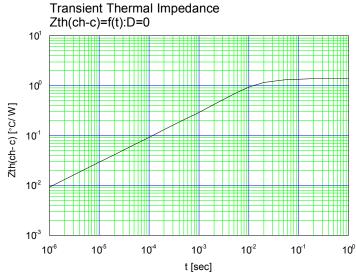












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